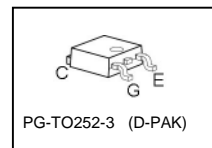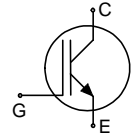# IGD06N60T

TRENCHSTOP™ Series

Low Loss IGBT: IGBT in TRENCHSTOP™ and Fieldstop technology

Features:
- Very low $V_{CE(sat)}$ 1.5 V (typ.)
- Maximum Junction Temperature 175°C
- Short circuit withstand time 5μs
- TRENCHSTOP™ and Fieldstop technology for 600V applications offers :
  - very tight parameter distribution
  - high ruggedness, temperature stable behavior
- Low EMI
- Qualified according to JEDEC[1] for target applications
- Pb-free lead plating; RoHS compliant
- Complete product spectrum and PSpice Models : http://www.infineon.com/igbt/

PG-TO252-3 (D-PAK)

Applications:
- Variable Speed Drive for washing machines and air conditioners
- Buck converters

Type	V_{CE}	$I_{C;Tc=100°C}$	$V_{CE(sat),Tj=25°C}$	$T_{j,max}$	Marking	Package
IGD06N60T	600V	6A	1.5V	175°C	G06T60	PG-TO252-3

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage, $T_j \geq 25°C$	V_{CE}	600	V
DC collector current, limited by T_{jmax} $T_C = 25°C$ $T_C = 100°C$	I_C	12 6	A
Pulsed collector current, t_p limited by T_{jmax}	I_{Cpuls}	18	
Turn off safe operating area, $V_{CE} = 600V$, $T_j = 175°C$, $t_p = 1μs$	-	18	
Gate-emitter voltage	V_{GE}	±20	V
Short circuit withstand time[2] $V_{GE} = 15V$, $V_{CC} \leq 400V$, $T_j \leq 150°C$	t_{SC}	5	μs
Power dissipation $T_C = 25°C$	P_{tot}	88	W
Operating junction temperature	T_j	-40...+175	°C
Storage temperature	T_{stg}	-55...+150	°C
Soldering temperature reflow soldering, MSL1		260	

[1] J-STD-020 and JESD-022
[2] Allowed number of short circuits: <1000; time between short circuits: >1s.

Thermal Resistance

Parameter	Symbol	Conditions	Max. Value	Unit
Characteristic				
IGBT thermal resistance, junction – case	R_{thJC}		1.7	K/W
Thermal resistance, junction – ambient	R_{thJA}		62	

Electrical Characteristic, at T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Static Characteristic						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0V$, $I_C=0.25mA$	600	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	V_{GE} = 15V, $I_C=6A$				
		$T_j=25°C$	-	1.5	2.05	
		$T_j=175°C$	-	1.8		
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C=0.18mA$, $V_{CE}=V_{GE}$	4.1	4.6	5.7	
Zero gate voltage collector current	I_{CES}	$V_{CE}=600V$, $V_{GE}=0V$				µA
		$T_j=25°C$	-	-	40	
		$T_j=175°C$	-	-	700	
Gate-emitter leakage current	I_{GES}	$V_{CE}=0V, V_{GE}=20V$	-	-	100	nA
Transconductance	g_{fs}	$V_{CE}=20V$, $I_C=6A$	-	3.6	-	S
Integrated gate resistor	R_{Gint}		none			Ω

Dynamic Characteristic

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Input capacitance	C_{iss}	$V_{CE}=25V$,	-	368	-	pF
Output capacitance	C_{oss}	$V_{GE}=0V$,	-	28	-	
Reverse transfer capacitance	C_{rss}	$f=1MHz$	-	11	-	
Gate charge	Q_{Gate}	$V_{CC}=480V$, $I_C=6A$ $V_{GE}=15V$	-	42	-	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	L_E		-	7	-	nH
Short circuit collector current[1]	$I_{C(SC)}$	$V_{GE}=15V, t_{SC}\leq5\mu s$ V_{CC} = 400V, T_j = 25°C	-	55	-	A

[1] Allowed number of short circuits: <1000; time between short circuits: >1s.

Switching Characteristic, Inductive Load, at T_j=25 °C

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
IGBT Characteristic						
Turn-on delay time	$t_{d(on)}$	T_j=25°C, V_{CC}=400V, I_C=6A, V_{GE}=0/15V, r_G=23Ω, L_σ=60nH, C_σ=40pF	-	9	-	ns
Rise time	t_r		-	6	-	
Turn-off delay time	$t_{d(off)}$		-	130	-	
Fall time	t_f		-	58	-	
Turn-on energy	E_{on}	L_σ, C_σ from Fig. E Energy losses include "tail" and diode reverse recovery. Diode used IDP06E60	-	0.09	-	mJ
Turn-off energy	E_{off}		-	0.11	-	
Total switching energy	E_{ts}		-	0.2	-	

Switching Characteristic, Inductive Load, at T_j=175 °C

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
IGBT Characteristic						
Turn-on delay time	$t_{d(on)}$	T_j=175°C, V_{CC}=400V, I_C=6A, V_{GE}=0/15V, r_G= 23Ω L_σ=60nH, C_σ=40pF	-	9	-	ns
Rise time	t_r		-	8	-	
Turn-off delay time	$t_{d(off)}$		-	165	-	
Fall time	t_f		-	84	-	
Turn-on energy	E_{on}	L_σ, C_σ from Fig. E Energy losses include "tail" and diode reverse recovery. Diode used IDP06E60	-	0.14	-	mJ
Turn-off energy	E_{off}		-	0.18	-	
Total switching energy	E_{ts}		-	0.335	-	
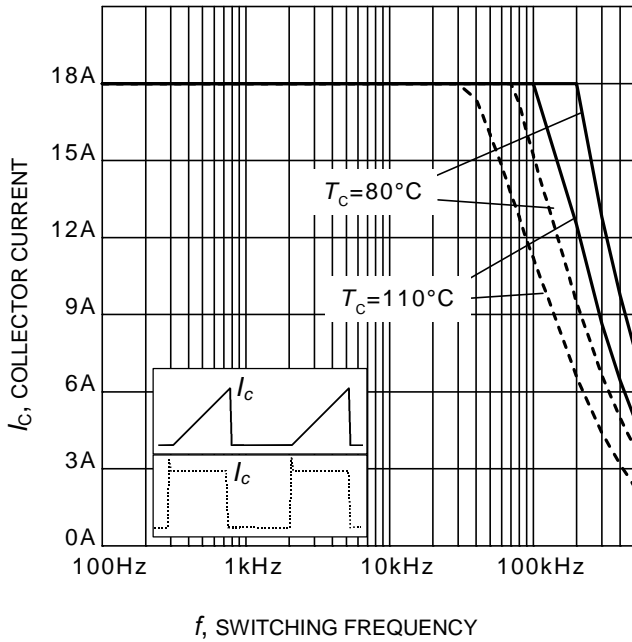
Figure 1. Collector current as a function of switching frequency
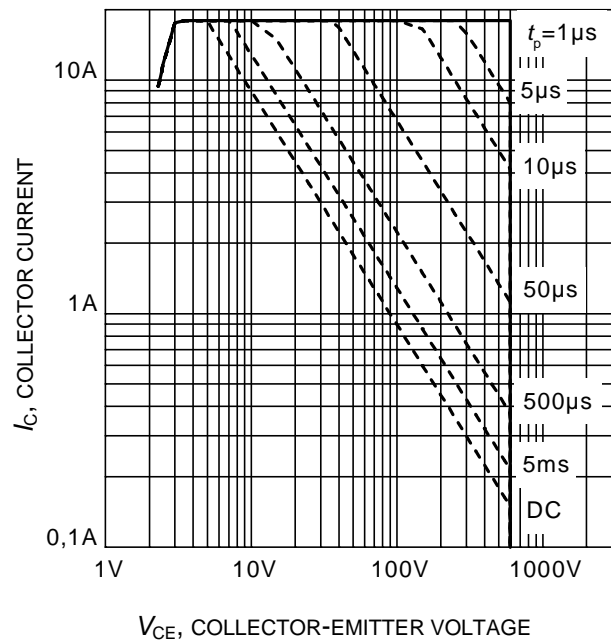($T_j \leq 175°C$, $D = 0.5$, $V_{CE} = 400V$,
$V_{GE} = 0/15V$, $r_G = 23\Omega$)

Figure 2. Safe operating area
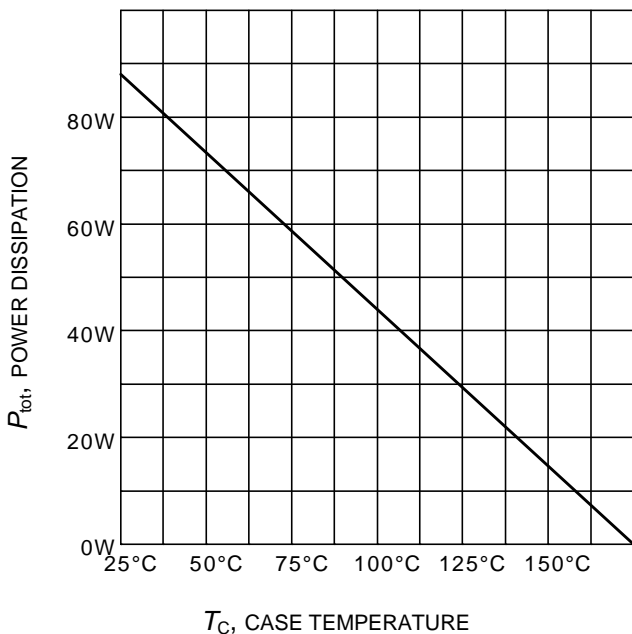($D = 0$, $T_C = 25°C$,
$T_j \leq 175°C$; $V_{GE} = 0/15V$)

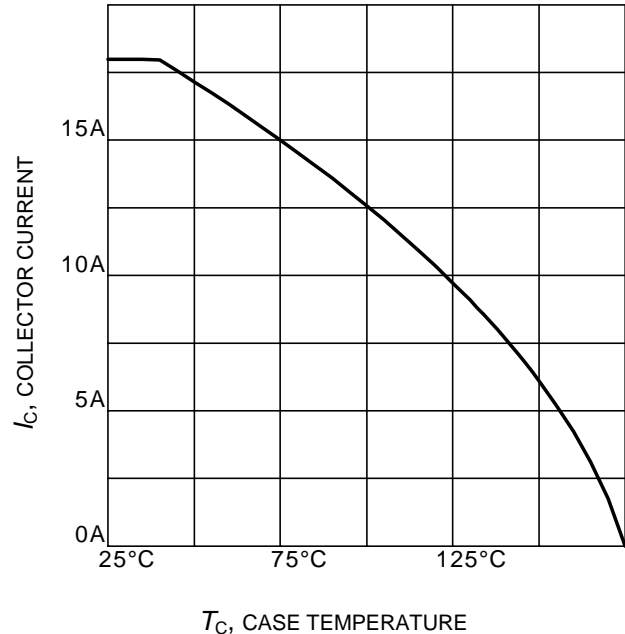**Figure 3. Power dissipation as a function of case temperature**
($T_j \leq 175°C$)

Figure 4. Collector current as a function of case temperature
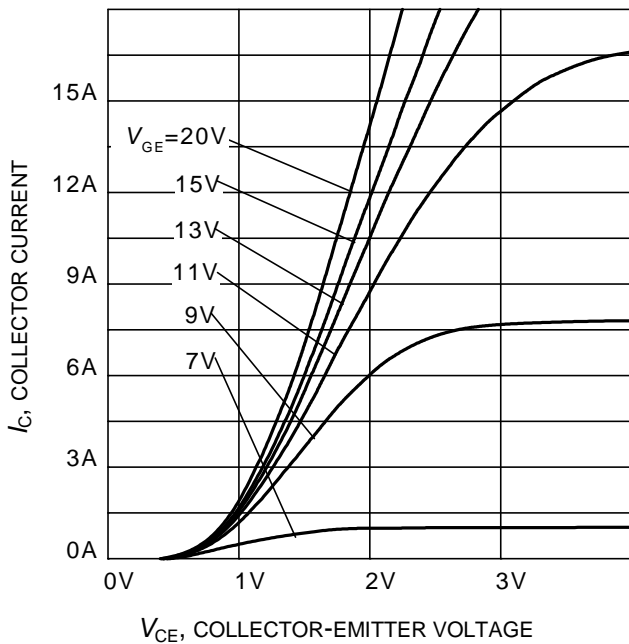($V_{GE} \geq 15V$, $T_j \leq 175°C$)

Figure 5.   Typical output characteristic
(T_j = 25°C)
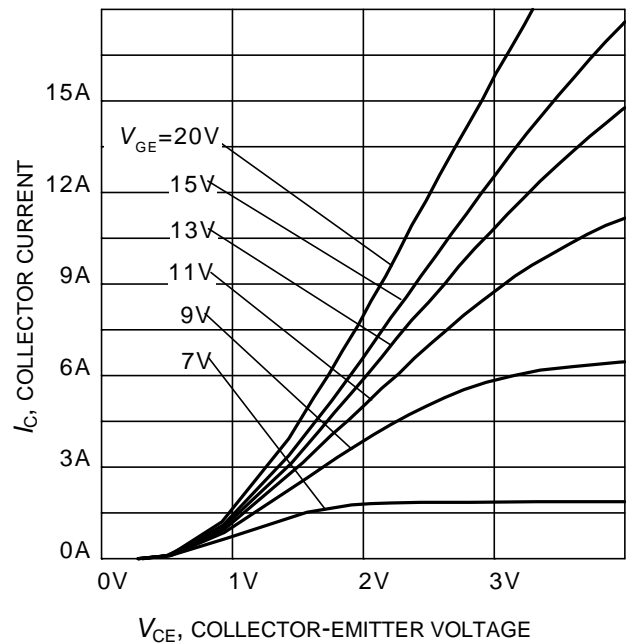
Figure 6.   Typical output characteristic
(T_j = 175°C)
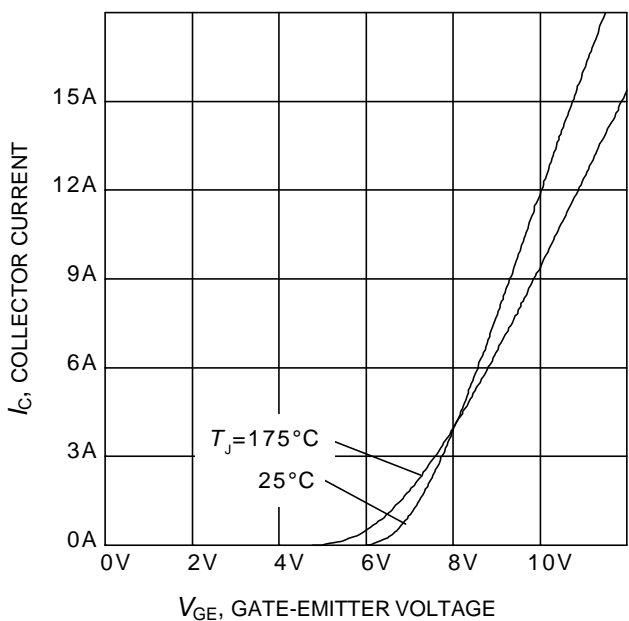
Figure 7.   Typical transfer characteristic
(V_{CE}=20V)
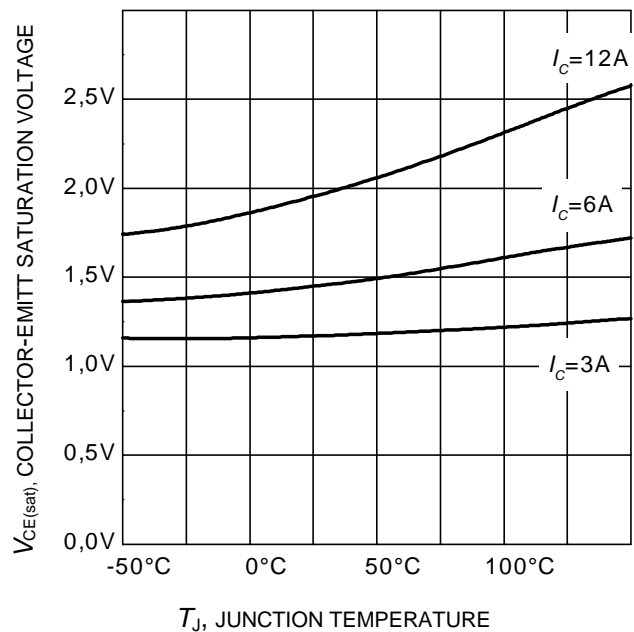
Figure 8.   Typical collector-emitter saturation voltage as a function of junction temperature
(V_{GE} = 15V)
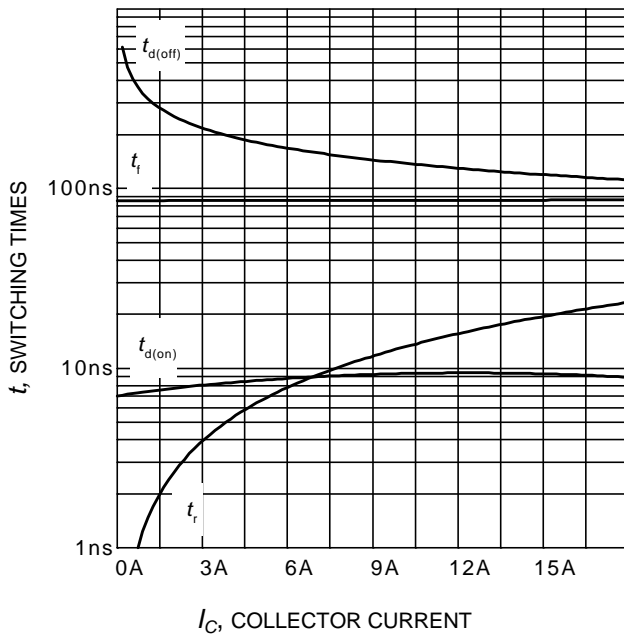
Figure 9. Typical switching times as a function of collector current
(inductive load, T_J=175°C, V_{CE} = 400V, V_{GE} = 0/15V, r_G = 23Ω, Dynamic test circuit in Figure E)
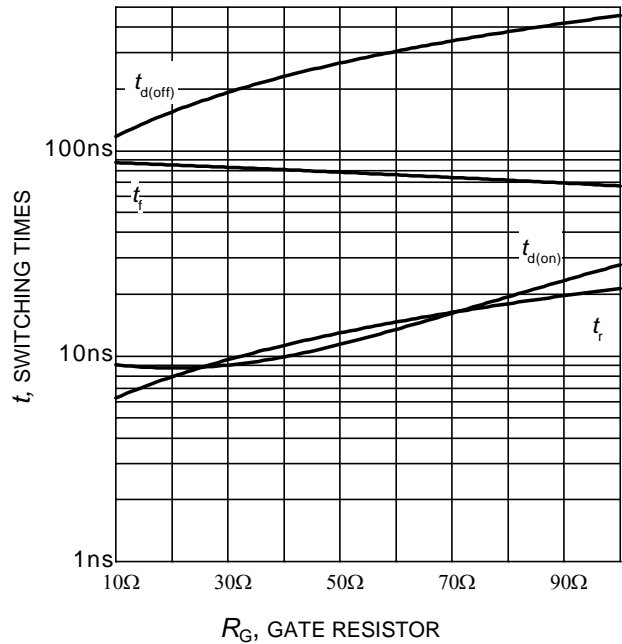
Figure 10. Typical switching times as a function of gate resistor
(inductive load, T_J=175°C, V_{CE} = 400V, V_{GE} = 0/15V, I_C = 6A, Dynamic test circuit in Figure E)
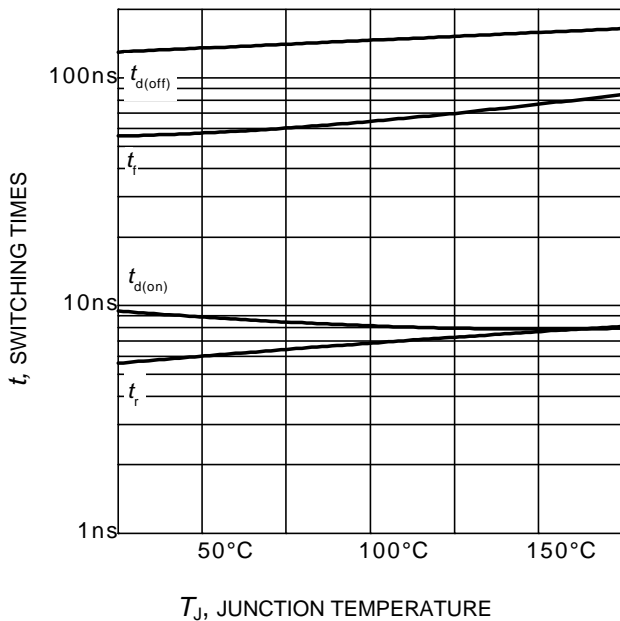
Figure 11. Typical switching times as a function of junction temperature
(inductive load, V_{CE} = 400V, V_{GE} = 0/15V, I_C = 6A, r_G = 23Ω, Dynamic test circuit in Figure E)

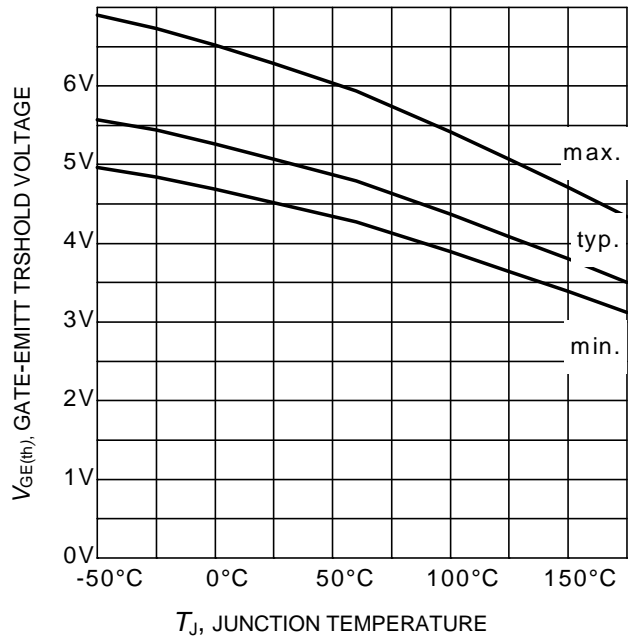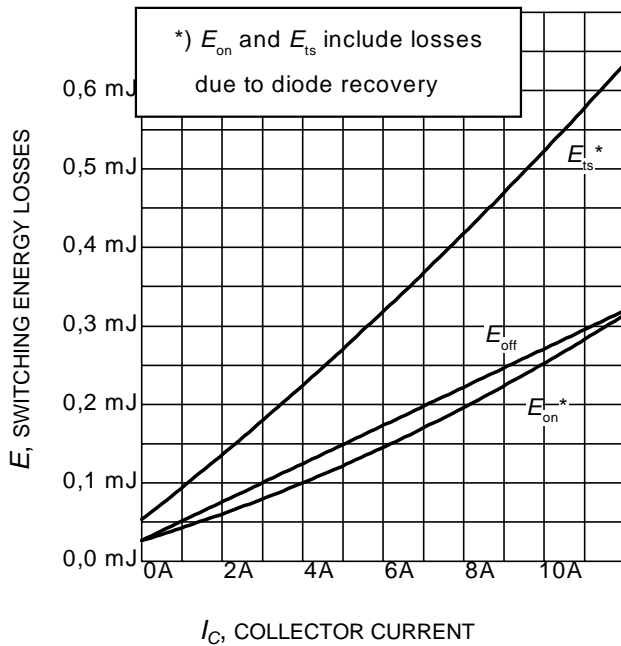**Figure 12. Gate-emitter threshold voltage as a function of junction temperature**
(I_C = 0.18mA)

Figure 13. Typical switching energy losses as a function of collector current
(inductive load, T_J=175°C, V_{CE}=400V, V_{GE}=0/15V, r_G=23Ω, Dynamic test circuit in Figure E)

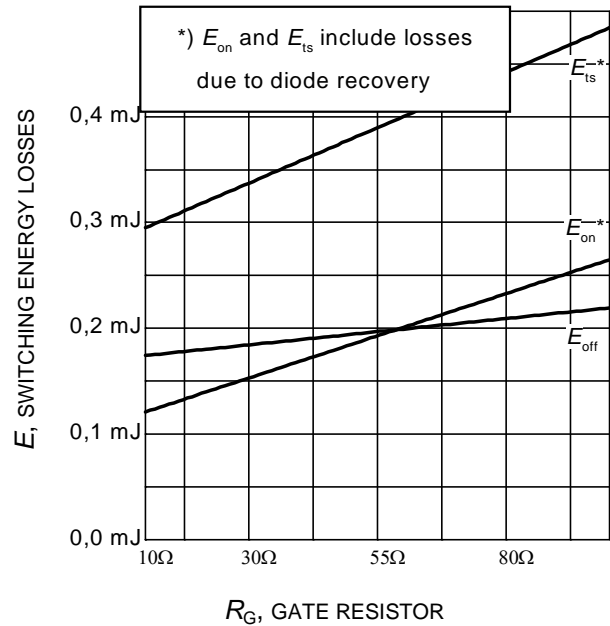**Figure 14. Typical switching energy losses as a function of gate resistor**
(inductive load, T_J=175°C, V_{CE} = 400V, V_{GE} = 0/15V, I_C = 6A, Dynamic test circuit in Figure E)

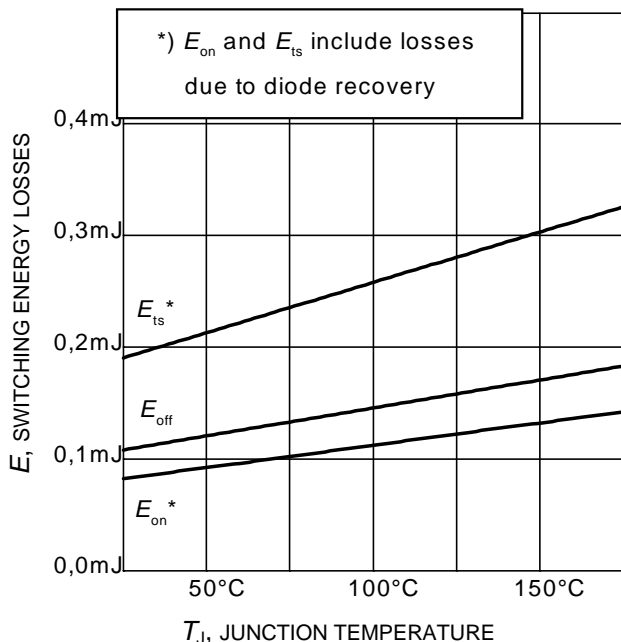**Figure 15. Typical switching energy losses as a function of junction temperature**
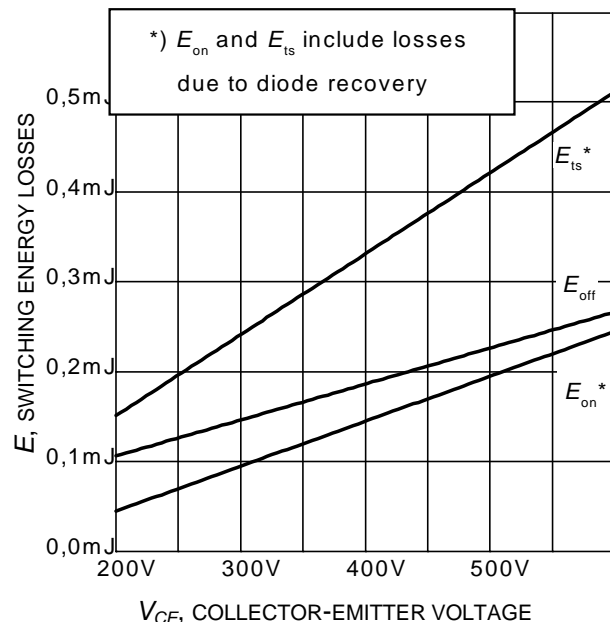(inductive load, V_{CE}=400V, V_{GE} = 0/15V, I_C = 6A, r_G = 23Ω, Dynamic test circuit in Figure E)

Figure 16. Typical switching energy losses as a function of collector emitter voltage
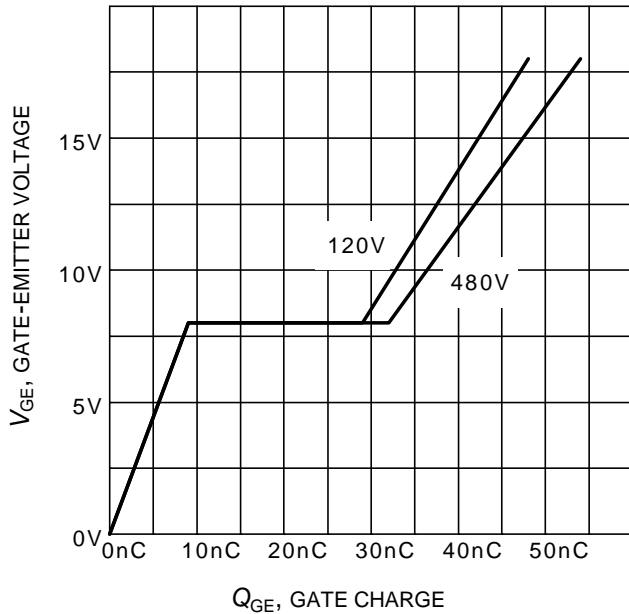(inductive load, T_J = 175°C, V_{GE} = 0/15V, I_C = 6A, r_G = 23Ω, Dynamic test circuit in Figure E)

Figure 17. Typical gate charge
($I_C = 6$ A)

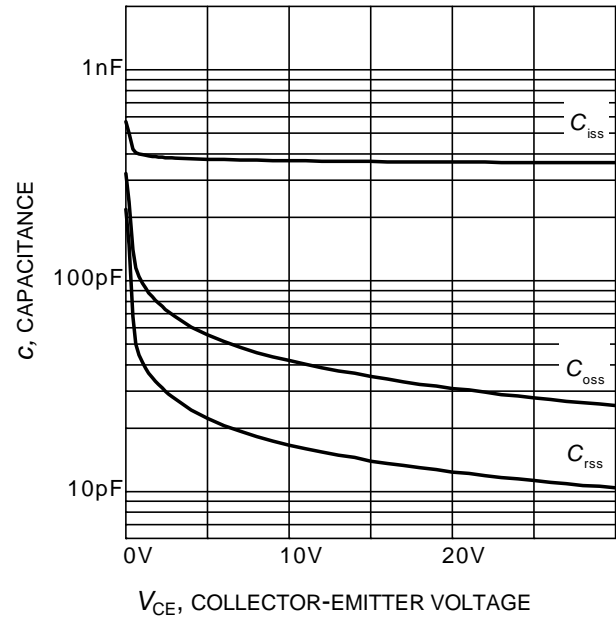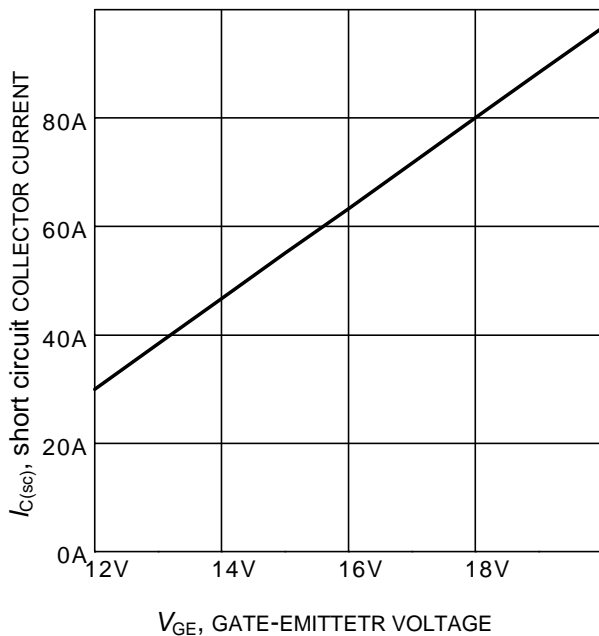**Figure 18. Typical capacitance as a function of collector-emitter voltage**
(V_{GE}=0V, f = 1 MHz)

Figure 19. Typical short circuit collector current as a function of gate-emitter voltage
($V_{CE} \leq 400$V, $T_j \leq 150°$C)

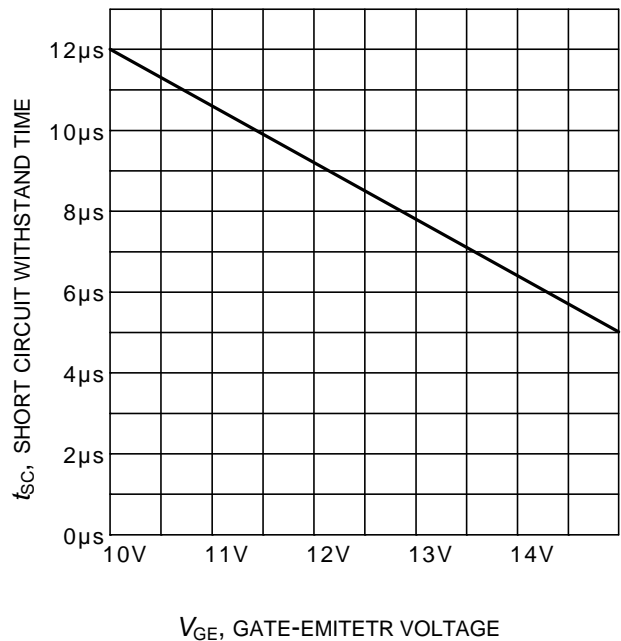**Figure 20. Short circuit withstand time as a function of gate-emitter voltage**
(V_{CE}=400V, start at T_J=25°C, T_{Jmax}<150°C)
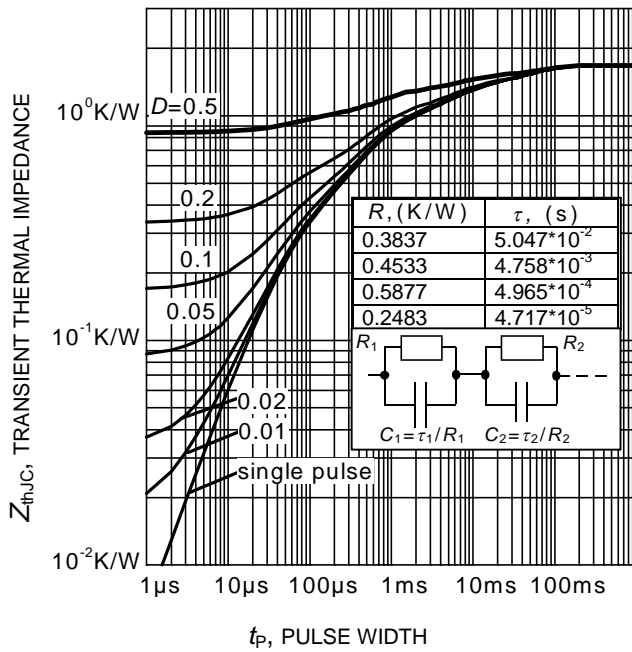
Figure 21. IGBT transient thermal impedance
$(D = t_\text{p} / T)$

The chart axes:
- Y-axis: Z_thJC, TRANSIENT THERMAL IMPEDANCE, ranging 10^{0}K/W, 10^{-1}K/W, 10^{-2}K/W
- X-axis: t_P, PULSE WIDTH, ranging 1µs, 10µs, 100µs, 1ms, 10ms, 100ms
- Curves labeled $D=0.5$, 0.2, 0.1, 0.05, 0.02, 0.01, single pulse

R , (K / W)	τ , (s)
0.3837	$5.047*10^{-2}$
0.4533	$4.758*10^{-3}$
0.5877	$4.965*10^{-4}$
0.2483	$4.717*10^{-5}$

$C_1 = \tau_1 / R_1 \quad C_2 = \tau_2 / R_2$

PG‑TO252‑3
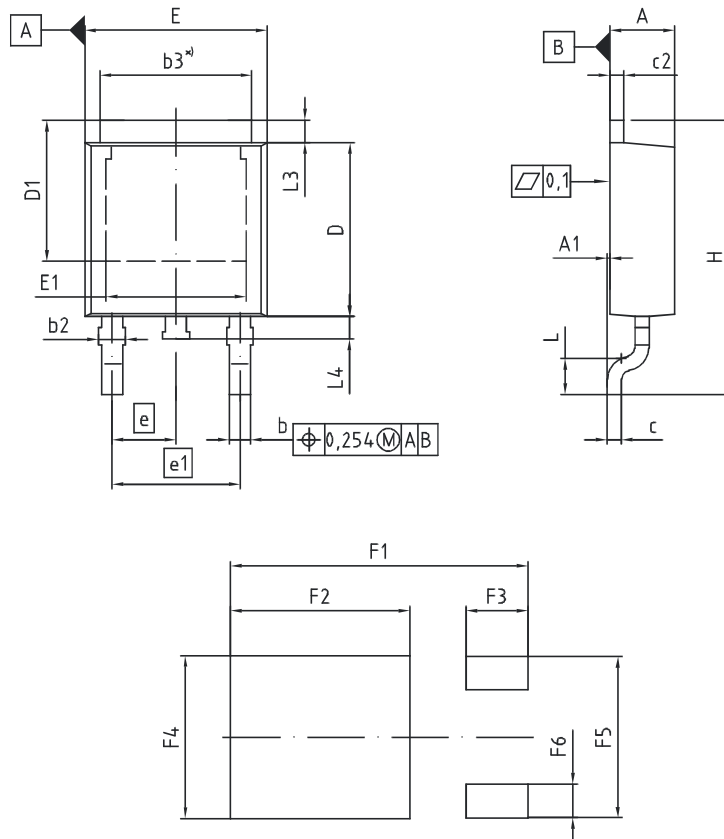
*) mold flash not included

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.16	2.41	0.085	0.095
A1	0.00	0.15	0.000	0.006
b	0.64	0.89	0.025	0.035
b2	0.65	1.15	0.026	0.045
b3	5.00	5.50	0.197	0.217
c	0.46	0.60	0.018	0.024
c2	0.46	0.98	0.018	0.039
D	5.97	6.22	0.235	0.245
D1	5.02	5.84	0.198	0.230
E	6.40	6.73	0.252	0.265
E1	4.70	5.21	0.185	0.205
e	2.29 (BSC)		0.090 (BSC)	
e1	4.57		0.180	
N	3		3	
H	9.40	10.48	0.370	0.413
L	1.18	1.70	0.046	0.067
L3	0.90	1.25	0.035	0.049
L4	0.51	1.00	0.020	0.039
F1	10.60		0.417	
F2	6.40		0.252	
F3	2.20		0.087	
F4	5.80		0.228	
F5	5.76		0.227	
F6	1.20		0.047	

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SCALE

EUROPEAN PROJECTION

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04

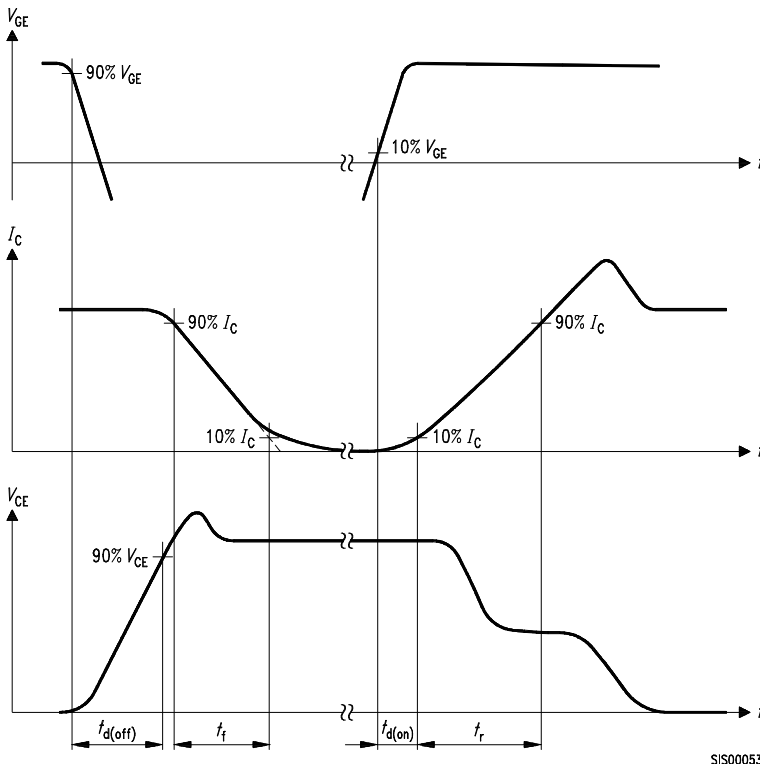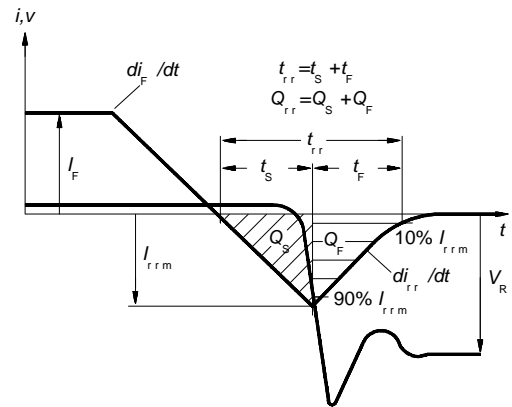Figure A. Definition of switching times
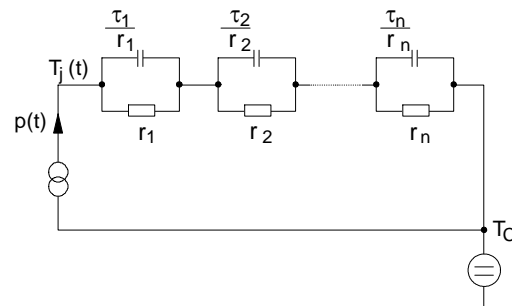

Figure B. Definition of switching losses

Figure C. Definition of diodes switching characteristics

Figure D. Thermal equivalent circuit

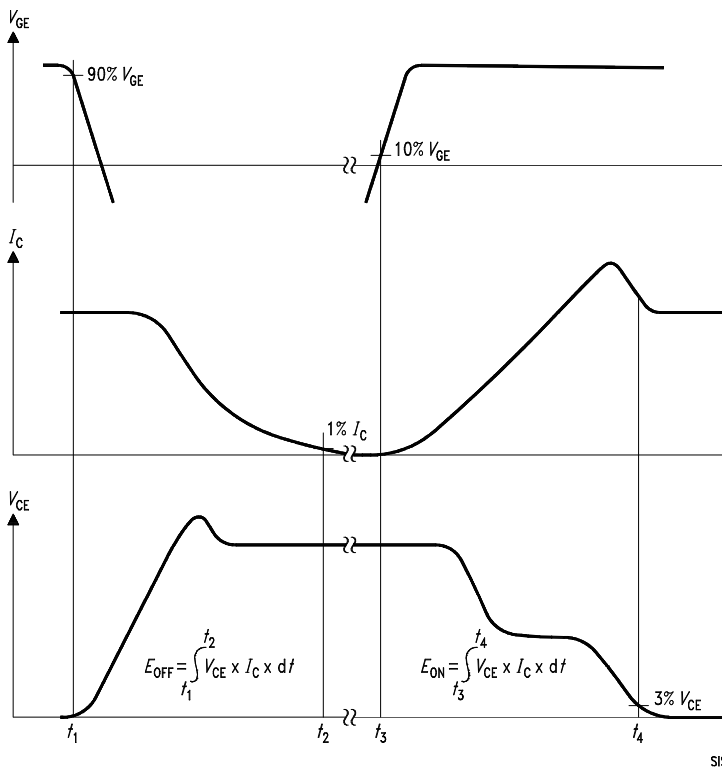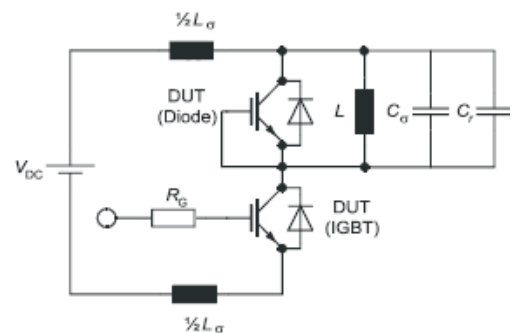**Figure E. Dynamic test circuit**
Parasitic inductance L_σ ,
Parasitic capacitor C_σ ,
Relief capacitor C_r
(only for ZVT switching)

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